

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00393	1.35	0.04185
	Doped silicon	Silicon (Si)	7440-21-3	0.28704	98.65	3.05815
		<b>Subtotal</b>		<b>0.29097</b>	<b>100</b>	<b>3.1</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03764	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01129	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03764	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.5512	99.77	400.0777
		<b>Subtotal</b>		<b>37.63777</b>	<b>100</b>	<b>401</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.85183	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.94132	10.0	63.3
	Filler	Silica fused	60676-86-0	50.50124	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11883	0.2	1.266
		<b>Subtotal</b>		<b>59.41322</b>	<b>100</b>	<b>633</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34649	100.0	25
		<b>Subtotal</b>		<b>2.34649</b>	<b>100</b>	<b>25</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11445	100.0	1.21933
		<b>Subtotal</b>		<b>0.11445</b>	<b>100</b>	<b>1.21933</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00394	2.0	0.042
	Lead alloy	Silver (Ag)	7440-22-4	0.00493	2.5	0.0525
	Lead alloy	Lead (Pb)	7439-92-1	0.18824	95.5	2.0055
		<b>Subtotal</b>		<b>0.19711</b>	<b>100</b>	<b>2.1</b>
		<b>Total</b>		<b>100.00001</b>	<b>100</b>	<b>1065.41933</b>

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